



Material Content Data Sheet



Sales Product Name		SPU07N60C3		Issued		20. July 2018		
MA#		MA000839088						
Package		PG-TO251-3-341		Weight*		383.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.883	1.27	1.27	12736	12736
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		179	
	non noble metal	iron	7439-89-6	0.229	0.06		598	
	non noble metal	copper	7440-50-8	228.946	59.71	59.79	597181	597958
	non noble metal	aluminium	7429-90-5	0.445	0.12	0.12	1160	1160
wire	inorganic material	antimonytrioxide	1309-64-4	1.700	0.44		4435	
encapsulation	plastics	brominated resin	-	1.822	0.48		4751	
	organic material	carbon black	1333-86-4	1.943	0.51		5068	
	plastics	epoxy resin	-	16.394	4.28		42762	
	inorganic material	silicondioxide	60676-86-0	99.578	25.97	31.68	259738	316754
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9756	9756
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1327	1327
solder	non noble metal	tin	7440-31-5	0.078	0.02		204	
	noble metal	silver	7440-22-4	0.098	0.03		256	
	non noble metal	lead	7439-92-1	3.742	0.98	1.03	9762	10222
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		50	
	non noble metal	copper	7440-50-8	19.177	5.00	5.00	50022	50087
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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